



LIN 2.1 / SAEJ2602-2, LIN Physical Layer

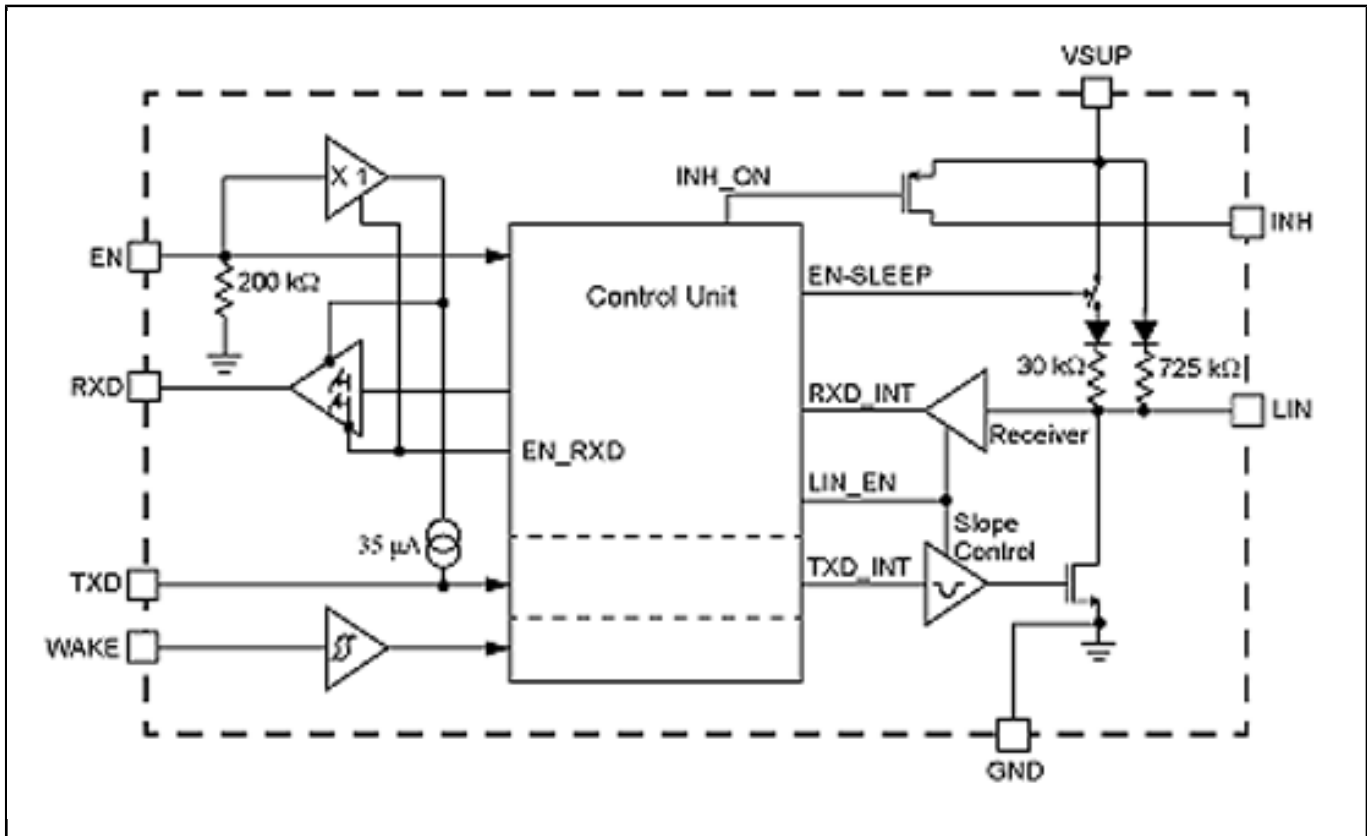
MC33662

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The NXP® MC33662 is a physical layer component dedicated to automotive LIN sub-bus applications.

- Designed to support automotive networks with Controller Area Network (CAN)
- Part number selection defines the operating baud rate (33662L or 33662S for 20 kB/s and 33662J for 10 kB/s)
- Both integrate a fast baud rate (100 kB/s) for test and programming modes
- Provides excellent Electromagnetic Compatibility (EMC) and Radiated Emission performance, Electrostatic Discharge (ESD) robustness and safe behaviour in case of TXD short to ground

MC33662_BD Block Diagram



View additional information for [LIN 2.1 / SAEJ2602-2, LIN Physical Layer](#).

Note: The information on this document is subject to change without notice.

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